Abstract of the Disclosure

Disclosed are a method and a system for manufacturing a semiconductor device by which it is possible to manufacture a semiconductor device while enabling evaluation of a manufacturing process for a super-miniaturized actual circuit pattern at a high speed by utilizing a three-dimensional measuring technique based on the use of an optical scatterometry apparatus. The method of manufacturing a semiconductor device comprising the step of forming a test pattern and an actual circuit pattern by a predetermined semiconductor manufacturing process, to thereby manufacture a product semiconductor device, wherein features of the three-dimensional shape of the test pattern formed in the product semiconductor device are measured by use of the optical scatterometry apparatus, and the semiconductor manufacturing process for the actual circuit pattern of the product semiconductor device is thereby evaluated.